

Product Change Notification

(Notification - P1902008-DIGI)

(MCP-AC-19-0008 / DOE001 / 4)

February 6, 2019

To: *Our Valued Digi-Key Electronics Customer*

Overview: The purpose of this notification is to communicate a product change of select Renesas Electronics America, Inc. (REA) devices.

This notification announces the following changes for select RL78/G12 devices (see Appendix 1 for details)...

1. The addition of Renesas Semiconductor Manufacturing Saijo as a wafer fabrication site.
2. Bonding wire material change from Gold (Au) to Copper (Cu).
3. Die mount material change.

There is a change to the part number. There is no change to electrical characteristics or product reliability.

Affected Products: A review of our records indicates the list of products in Appendix 2 may affect your company.

Part numbers given in this list are for active part numbers in REA database at the time of this notification.

Key Dates:

Shipments from REA of product from new wafer fabrication site begins.

August 1st, 2019

Response: No response is required. REA will consider this notification approved 30 days after its issue. If you anticipate volumes beyond your regular rate prior to the transition date, please contact your REA sales representative with a forecast of your requirements.

If the customer provides a timely acknowledgement, the customer shall have 90 days (an additional 60 days) from the date of receipt of this notification in which to make any objections to the notification. If the customer does not make any objections to this notification within 90 days of the receipt of the notification, then Renesas will consider the notification as approved. If customer cannot accept the notification, then the customer must provide Renesas with a last time buy demand and purchase order.

Please contact your REA sales representative for any questions or comments.

Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.

Appendix 1: Change Summary

Item		Current	New
Wafer fabrication factory		Kawashiri	Kawashiri / Saijo
Assembly factory		RSB	
Sorting factory		RSB	
Package	Outline	No change	
Lead frame	Material	No change	
	Inner pattern	No change	
Die mount material	Material	No change (Ag epoxy paste)	Change (Ag epoxy paste)
Bonding wire	Material	Au	Cu (Pd coating)
Resin	Material	No change	
Plating	Material	No change	
Marking	Font	No change	
	Digit number	No change	
Packing	Tray / Emboss tape	No change	

※ There is no impact on reliability and specification by material change.

Appendix 2: List of Digi-Key Affected Products

Booking PN	Replacement PN	Booking PN	Replacement PN
R5F10266ASP#V0	R5F10266ASP#35	R5F1026AASP#X5	R5F1026AASP#55
R5F10266ASP#V5	R5F10266ASP#35	R5F1026ADSP#V0	R5F1026ADSP#35
R5F10266ASP#X0	R5F10266ASP#55	R5F1026ADSP#V5	R5F1026ADSP#35
R5F10266ASP#X5	R5F10266ASP#55	R5F1026ADSP#X0	R5F1026ADSP#55
R5F10266DSP#V0	R5F10266DSP#35	R5F1026ADSP#X5	R5F1026ADSP#55
R5F10266DSP#V5	R5F10266DSP#35	R5F1026AGSP#V0	R5F1026AGSP#35
R5F10266DSP#X0	R5F10266DSP#55	R5F1026AGSP#V5	R5F1026AGSP#35
R5F10266DSP#X5	R5F10266DSP#55	R5F1026AGSP#X0	R5F1026AGSP#55
R5F10266GSP#V0	R5F10266GSP#35	R5F1026AGSP#X5	R5F1026AGSP#55
R5F10266GSP#V5	R5F10266GSP#35	R5F10366ASP#V0	R5F10366ASP#35
R5F10266GSP#X0	R5F10266GSP#55	R5F10366ASP#V5	R5F10366ASP#35
R5F10266GSP#X5	R5F10266GSP#55	R5F10366ASP#X0	R5F10366ASP#55
R5F10267ASP#V0	R5F10267ASP#35	R5F10366ASP#X5	R5F10366ASP#55
R5F10267ASP#V5	R5F10267ASP#35	R5F10366AXXSP#X5	R5F10366AXXSP#55
R5F10267ASP#X0	R5F10267ASP#55	R5F10366DSP#V0	R5F10366DSP#35
R5F10267ASP#X5	R5F10267ASP#55	R5F10366DSP#V5	R5F10366DSP#35
R5F10267AXXSP#V0	R5F10267AXXSP#35	R5F10366DSP#X0	R5F10366DSP#55
R5F10267AXXSP#X0	R5F10267AXXSP#55	R5F10366DSP#X5	R5F10366DSP#55
R5F10267DSP#V0	R5F10267DSP#35	R5F10367ASP#V0	R5F10367ASP#35
R5F10267DSP#V5	R5F10267DSP#35	R5F10367ASP#V5	R5F10367ASP#35
R5F10267DSP#X0	R5F10267DSP#55	R5F10367ASP#X0	R5F10367ASP#55
R5F10267DSP#X5	R5F10267DSP#55	R5F10367ASP#X5	R5F10367ASP#55
R5F10267GSP#V0	R5F10267GSP#35	R5F10367AXXSP#X5	R5F10367AXXSP#55
R5F10267GSP#V5	R5F10267GSP#35	R5F10367DSP#V0	R5F10367DSP#35
R5F10267GSP#X5	R5F10267GSP#55	R5F10367DSP#V5	R5F10367DSP#35
R5F10268ASP#V0	R5F10268ASP#35	R5F10367DSP#X0	R5F10367DSP#55
R5F10268ASP#V5	R5F10268ASP#35	R5F10367DSP#X5	R5F10367DSP#55
R5F10268ASP#X0	R5F10268ASP#55	R5F10368AA02SP#V0	R5F10368AA02SP#35
R5F10268ASP#X5	R5F10268ASP#55	R5F10368ASP#V0	R5F10368ASP#35
R5F10268AXXSP#V5	R5F10268AXXSP#35	R5F10368ASP#V5	R5F10368ASP#35
R5F10268AXXSP#X5	R5F10268AXXSP#55	R5F10368ASP#X0	R5F10368ASP#55
R5F10268DSP#V0	R5F10268DSP#35	R5F10368ASP#X5	R5F10368ASP#55
R5F10268DSP#V5	R5F10268DSP#35	R5F10368DSP#V0	R5F10368DSP#35
R5F10268DSP#X0	R5F10268DSP#55	R5F10368DSP#V5	R5F10368DSP#35
R5F10268DSP#X5	R5F10268DSP#55	R5F10368DSP#X0	R5F10368DSP#55
R5F10268GSP#V0	R5F10268GSP#35	R5F10368DSP#X5	R5F10368DSP#55
R5F10268GSP#V5	R5F10268GSP#35	R5F10369ASP#V0	R5F10369ASP#35
R5F10268GSP#X0	R5F10268GSP#55	R5F10369ASP#V5	R5F10369ASP#35
R5F10268GSP#X5	R5F10268GSP#55	R5F10369ASP#X0	R5F10369ASP#55
R5F10269ASP#V0	R5F10269ASP#35	R5F10369ASP#X5	R5F10369ASP#55
R5F10269ASP#V5	R5F10269ASP#35	R5F10369DSP#V0	R5F10369DSP#35
R5F10269ASP#X0	R5F10269ASP#55	R5F10369DSP#V5	R5F10369DSP#35
R5F10269ASP#X5	R5F10269ASP#55	R5F10369DSP#X0	R5F10369DSP#55
R5F10269DSP#V0	R5F10269DSP#35	R5F10369DSP#X5	R5F10369DSP#55
R5F10269DSP#V5	R5F10269DSP#35	R5F1036AASP#V0	R5F1036AASP#35
R5F10269DSP#X0	R5F10269DSP#55	R5F1036AASP#V5	R5F1036AASP#35
R5F10269DSP#X5	R5F10269DSP#55	R5F1036AASP#X0	R5F1036AASP#55
R5F10269GSP#V0	R5F10269GSP#35	R5F1036AASP#X5	R5F1036AASP#55
R5F10269GSP#V5	R5F10269GSP#35	R5F1036ADSP#V0	R5F1036ADSP#35
R5F10269GSP#X5	R5F10269GSP#55	R5F1036ADSP#V5	R5F1036ADSP#35
R5F1026AASP#V0	R5F1026AASP#35	R5F1036ADSP#X0	R5F1036ADSP#55
R5F1026AASP#V5	R5F1026AASP#35	R5F1036ADSP#X5	R5F1036ADSP#55
R5F1026AASP#X0	R5F1026AASP#55		